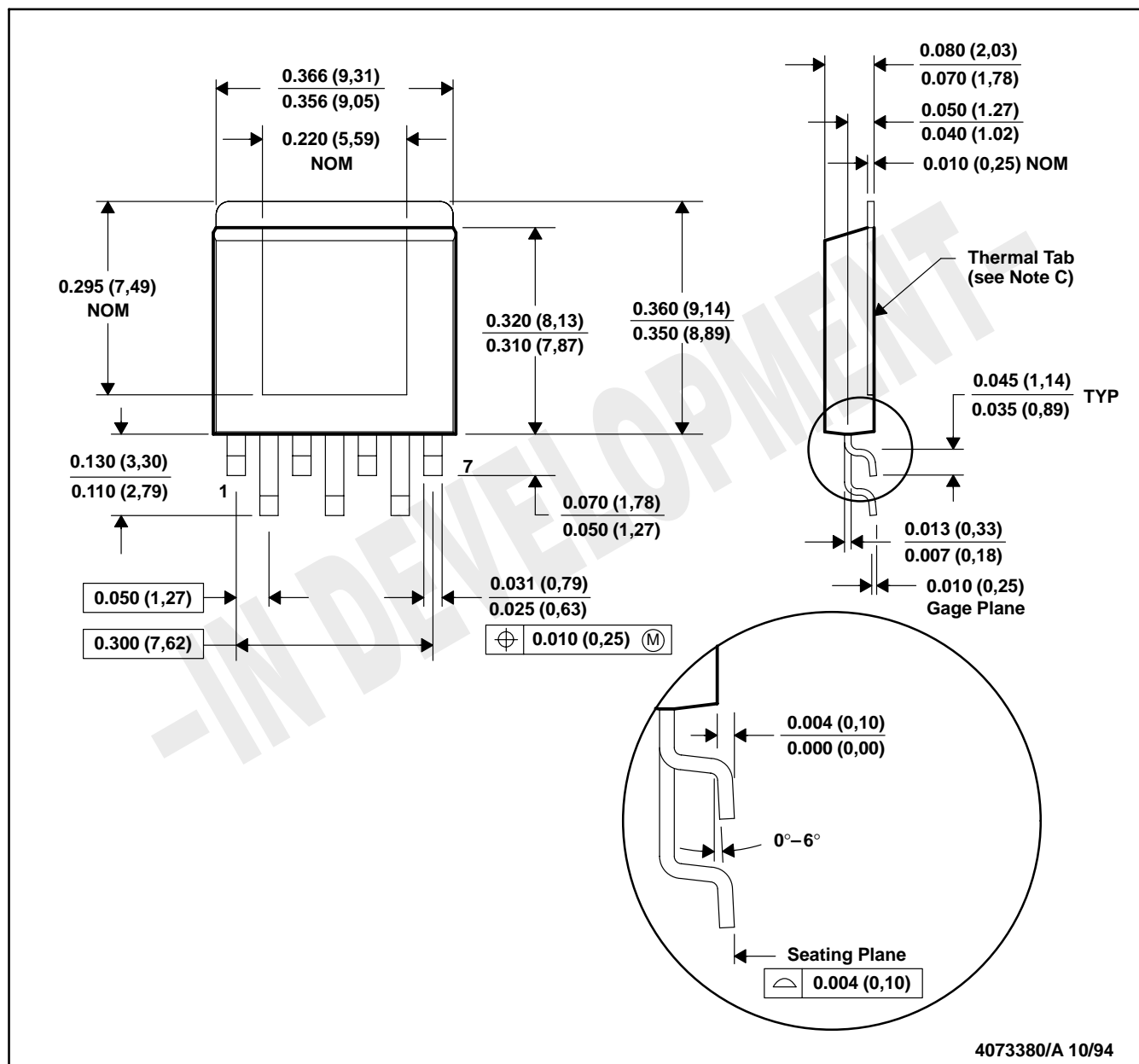


KTK (R-PSFM-G7)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. The center lead is in electrical contact with the thermal tab.



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